

# **Advanced Interconnect and Interconnect/Electrode Interfaces Development at PNNL**

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# Objectives and Approach

## ◆ Objectives

- Develop cost-effective, optimized materials and fabrication approaches for SOFC interconnect and interconnect/electrode interface (i.e. contacts) applications
- Identify and understand degradation processes in interconnects and interconnect/electrode interfaces

## ◆ Approach

- Materials and process development
  - Cost-effective oxidation resistant alloys
  - Surface modification via coatings
  - Interconnect/electrode contact materials
- Materials evaluation and degradation study
  - Screening study of alloys and ceramics for interconnect and interface applications, respectively
  - Investigation and understanding of oxidation/corrosion and interfacial reactions and stability under SOFC operating conditions.

# Accomplishments in FY07

- ◆ Investigation and development of cost-effective ferritic stainless steels (In collaboration with Allegheny Ludlum Corp.)
  - Systematically investigated 430
  - Identified and evaluated 439 and 441, two modified versions of 430
  - Applied protection layers onto candidate alloys and evaluated their performance
- ◆ Development of protection layers and fabrication approaches
  - Completed long-term thermal stability and electrical performance evaluation
  - Initiated optimization of materials and fabrication for further cost-reduction
- ◆ Investigation and development of contact layers between metallic interconnects and electrodes
  - Screening-studied more than a dozen materials systems via different fabrication approaches
  - Identified two promising material groups and three approaches
  - Evaluated electrical performance of selected candidates

# Investigation and Development of Novel Interconnect Alloys

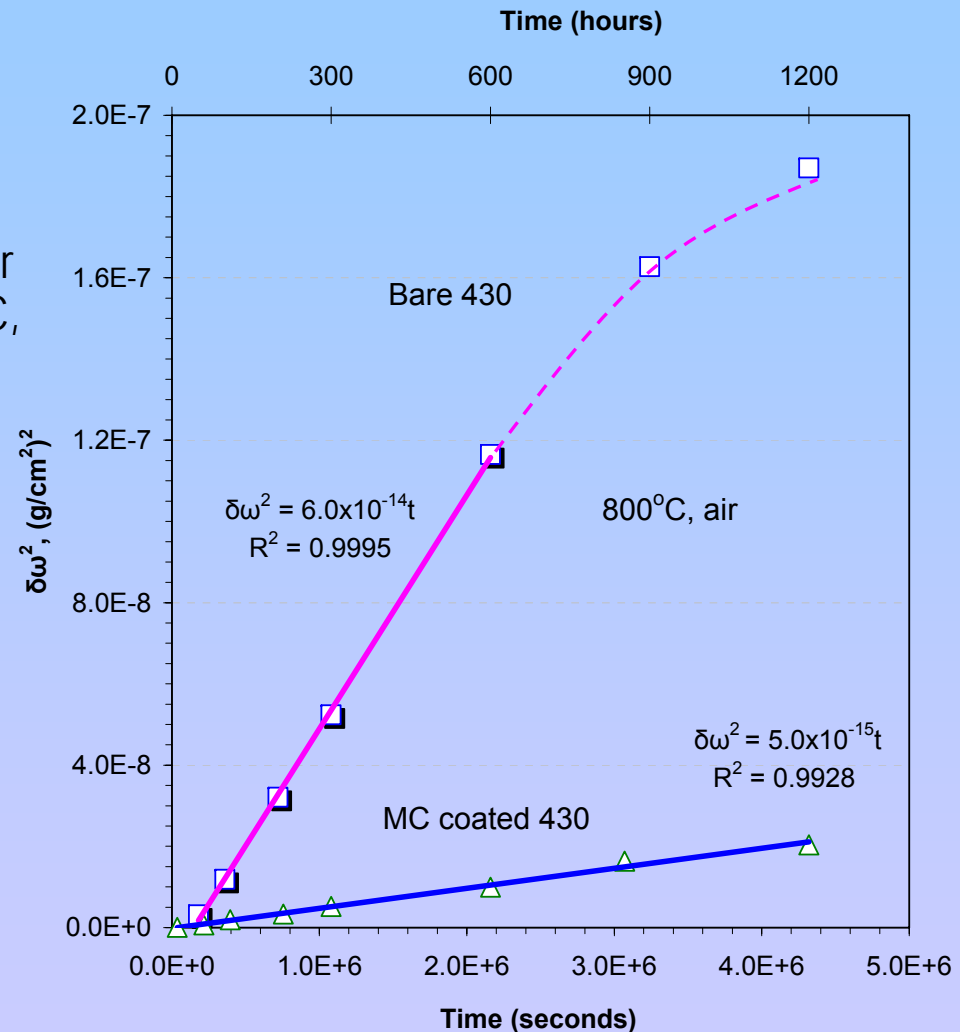
- ◆ **Goal:** Identify/develop a novel ferritic stainless steel (FSS) with an optimized alloy chemistry that offers comparable or improved performance relative to the state-of-the-art compositions such as Crofer 22 APU, **while being more cost-effective.**
- ◆ **Approach:** To achieve the desired alloy chemistry or control residual alloy elements of Si, C, N, etc., via alloying, instead of extra refining that adds cost.
- ◆ **Accomplishments**
  - Investigated properties of 430 relevant to interconnect applications
  - Identified potential candidates 441 and 439, two modified versions of 430
  - Evaluated their properties relative to interconnect requirements
  - Surface-modified the potential candidates with spinel protection layers and investigated their stability and electrical performance



# Oxidation Kinetics of Bare and Coated 430

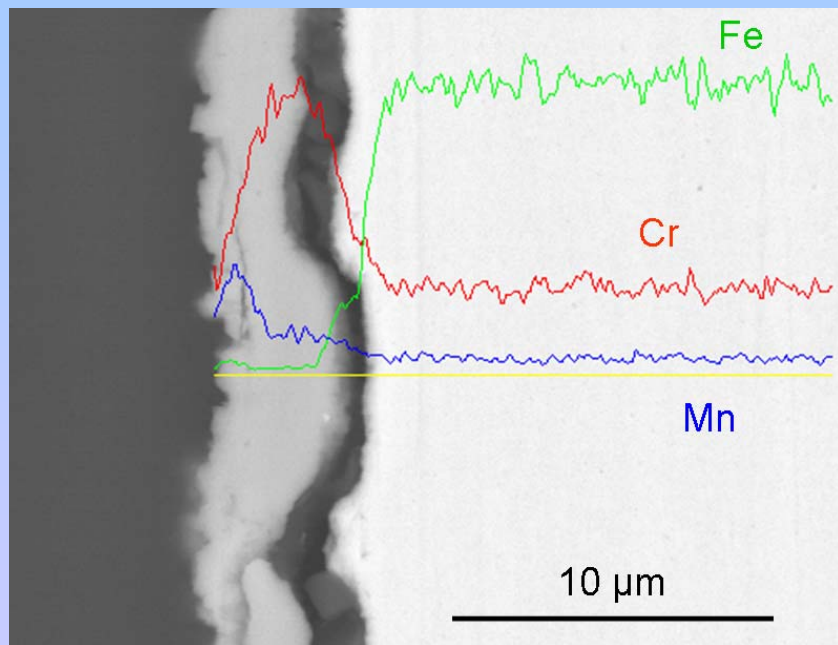
## Why 430: cost reduction

- 430: 17% Cr, via conventional melting – more cost-effective
- Crofer 22 APU: 23%Cr, extra refining (e.g. vacuum refining) for cleaning residual elements, Si, C, N, etc.
- Bare 430 demonstrated a fairly low scale growth rate at early stages
- Leveling off of the weight gain indicated likely spallation
- $\text{Mn}_{1.5}\text{Co}_{1.5}\text{O}_4$  (MC) spinel protection layers drastically mitigated the scale growth beneath the coating

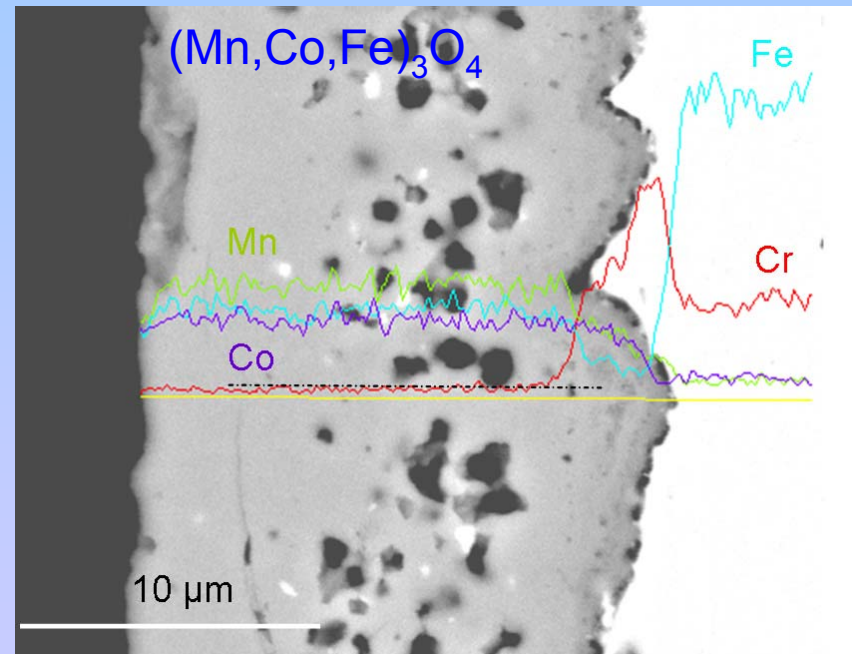


# Surface Stability of 430

- ❑ Unlike bare 430, no spallation observed on MC 430
- ❑ Fe transported through the coating, BUT not Cr
- ❑ No solubility of  $\text{SiO}_2$  in  $\text{Cr}_2\text{O}_3$
- ❑ Formation of continuous, insulating  $\text{SiO}_2$  layer b/w scale and Fe-Cr substrate



Bare 430

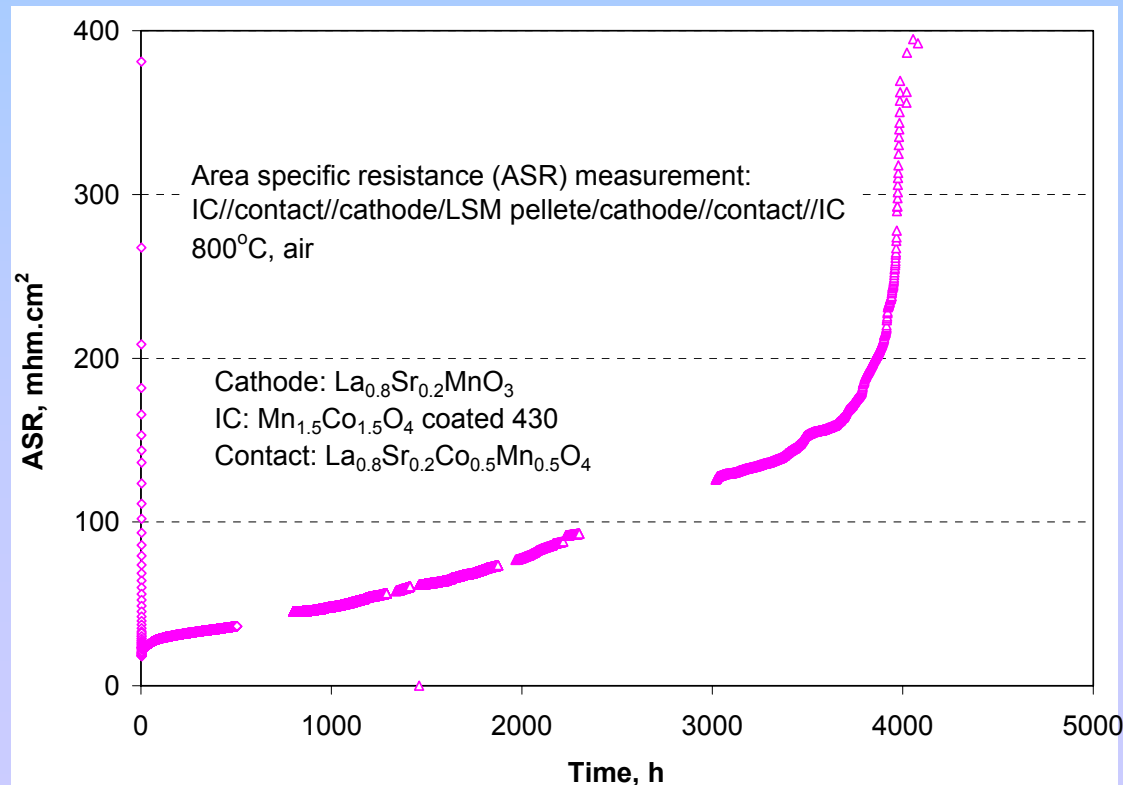


MC coated 430

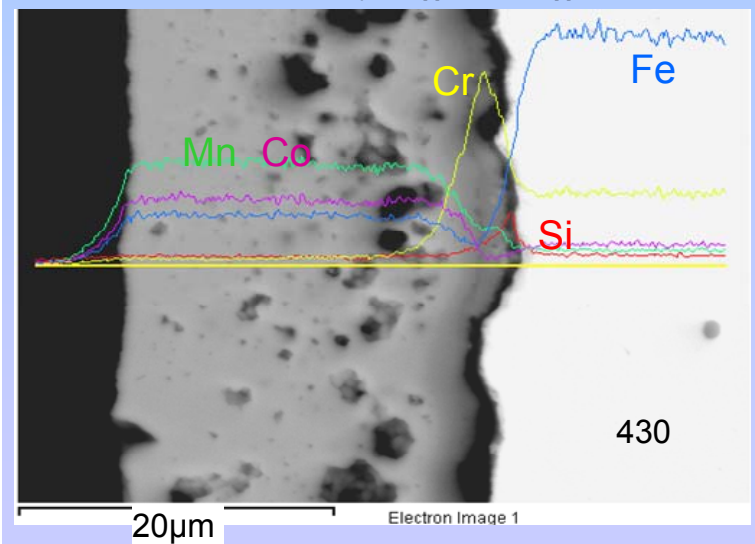
1,200 hrs, air, 800°C

# Long-Term Performance of MC Coated430

- The formation of a continuous insulating  $\text{SiO}_2$  layer at the scale/metal interface led to a high ASR.
- The ASR became unstable after about 4,000 hours, likely due to detachment of scale from the metal substrate.



MC protection layer||scale||Fe-Cr

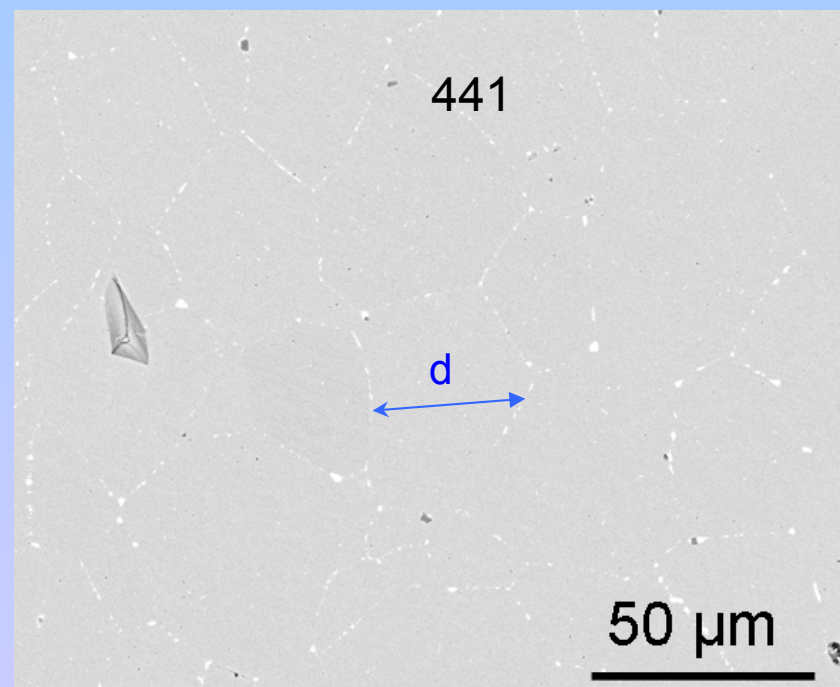




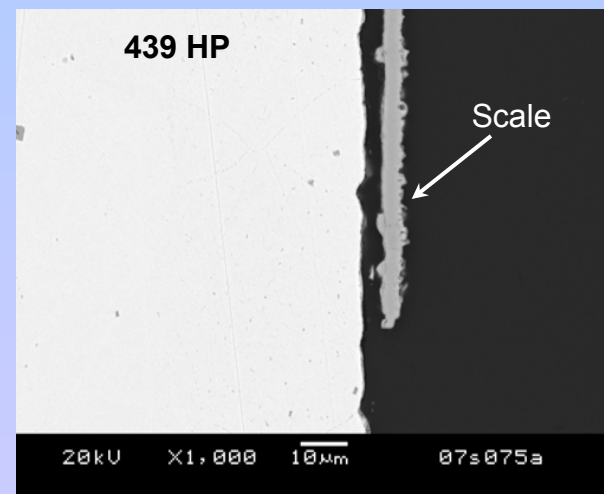
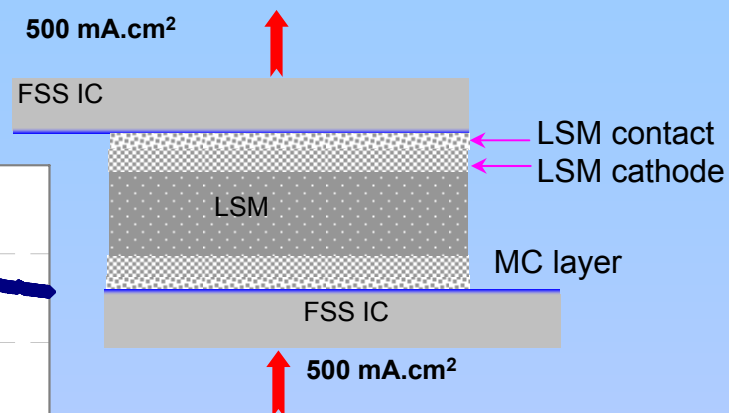
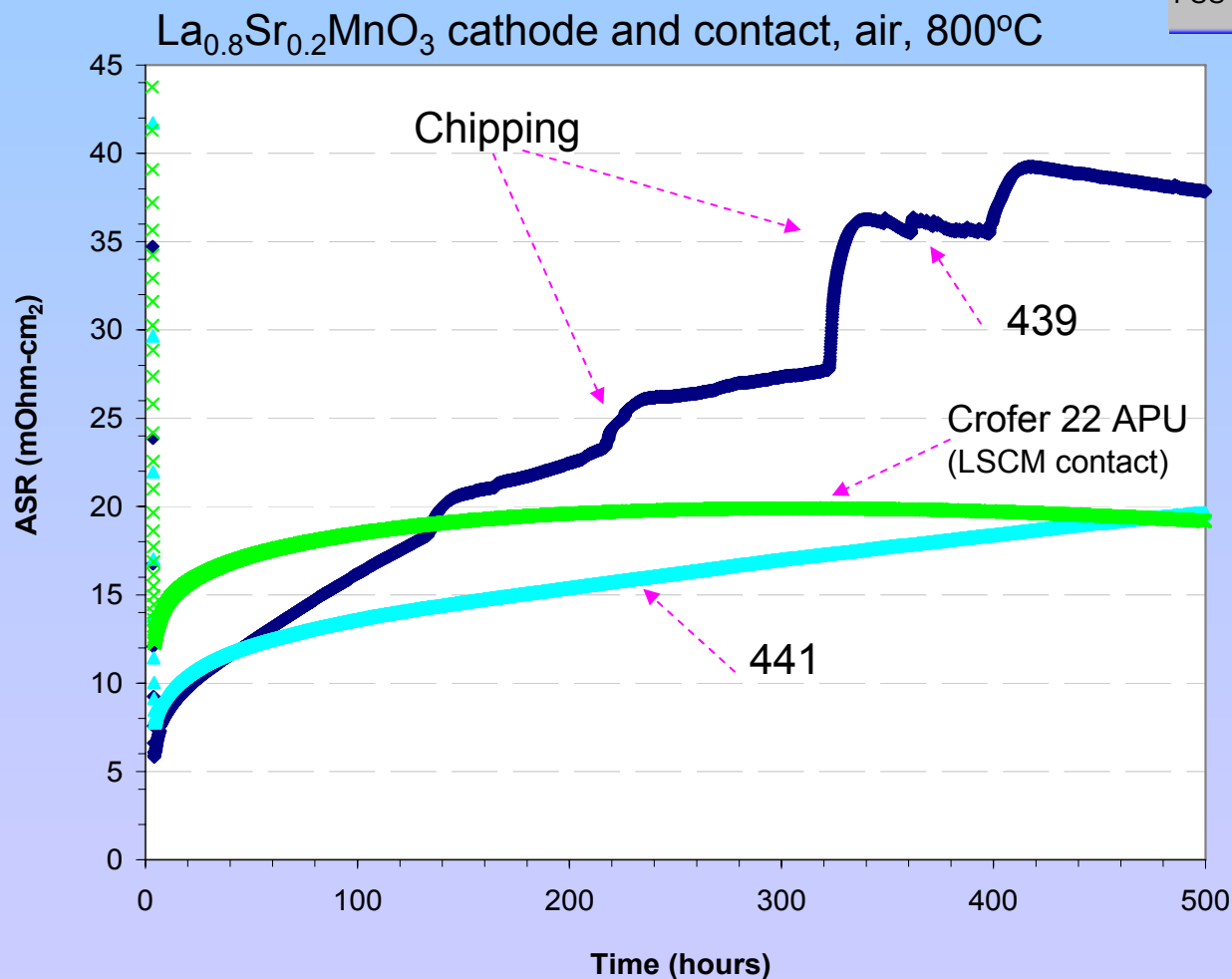
# Metallurgy of 441 and 439

Designation	Cr	Mn	Ni	C	Al	Si	P	S	Ti	Nb	Re
T-441	17.8	0.33	0.20	0.010	0.045	0.47	0.024	0.001	0.18	0.46	
439 HP	17.5	0.44	0.20	0.012	0.040	0.73	0.016	0.0004	0.41		
AL 430	17.0	≤1.0	≤0.75	≤0.12		≤1.0					
Crofer 22 APU	23.0	0.4-0.8		0.030	≤0.50	≤.50	0.020	0.050	≤0.2		0.04-0.20

- Fractional % of Ti and Ti/Nb were added into Fe-17%Cr substrate for 439 and 441, respectively
- Nb leads to laves phase ( $\text{Fe}_2\text{Nb}$ ) precipitation along grain boundaries that significantly improves high temperature strength and creep resistance of the Fe-Cr substrate (double yield strength at 800°C)
- As strong carbide/nitride formation elements, Ti and Nb lower interstitial elements C and N in the substrate
- Can Nb (or Ti) tie up Si to prevent  $\text{SiO}_2$  layer?

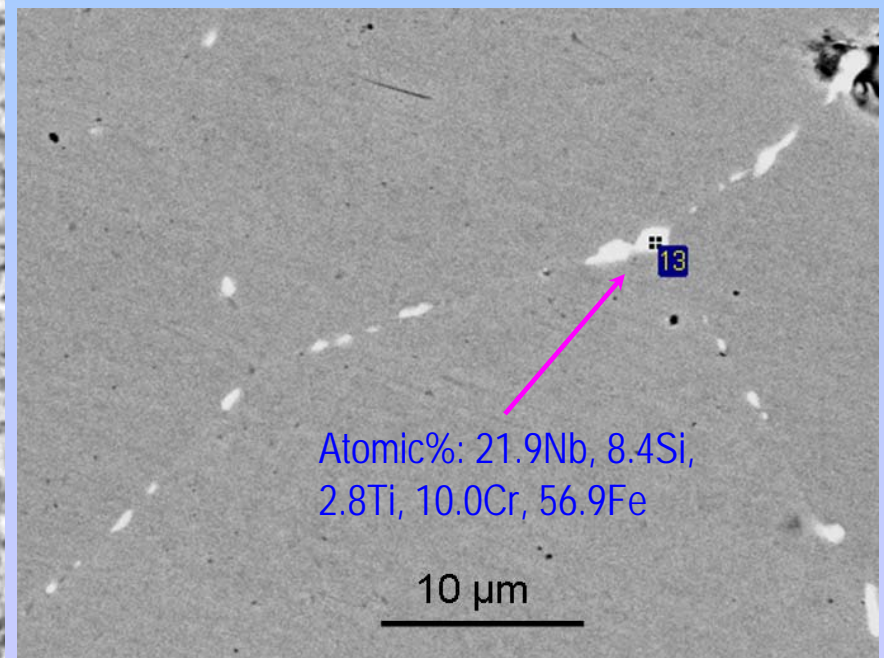
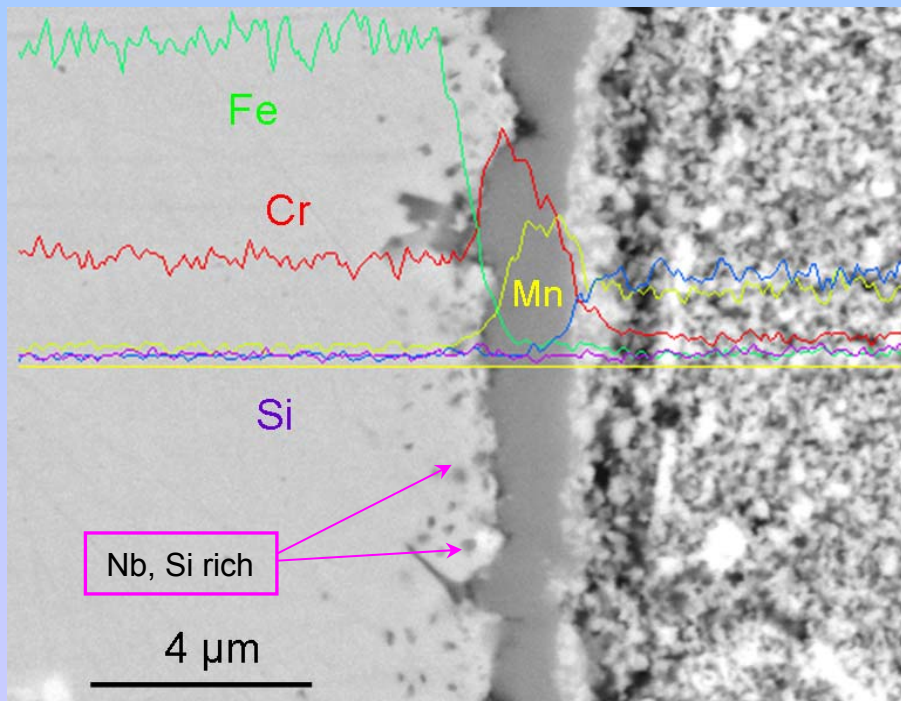


# Electrical Evaluation of 441 and 439



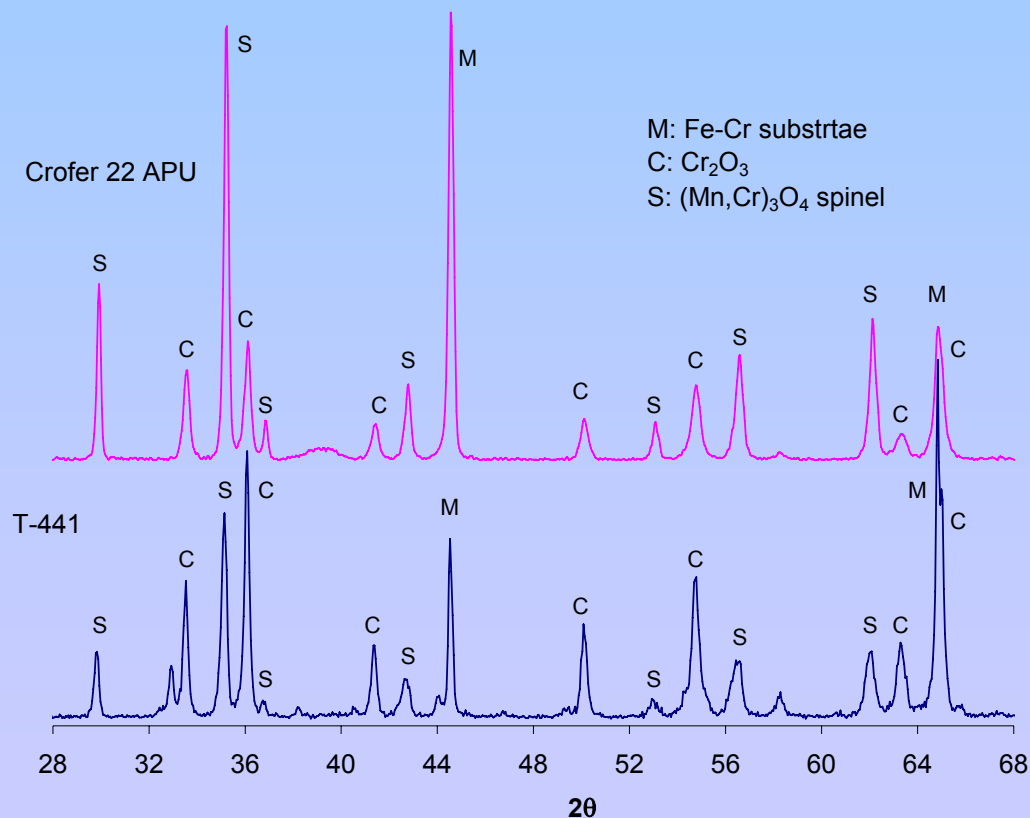
# Effects of Minor Alloying Elements in 441

- There was Si buildup or silica layer formation between scale/metal interface, in spite of about 0.5% residual Si in the metal substrate
- Nb tied up Si, preventing formation  $\text{SiO}_2$  layer at the scale/metal interface

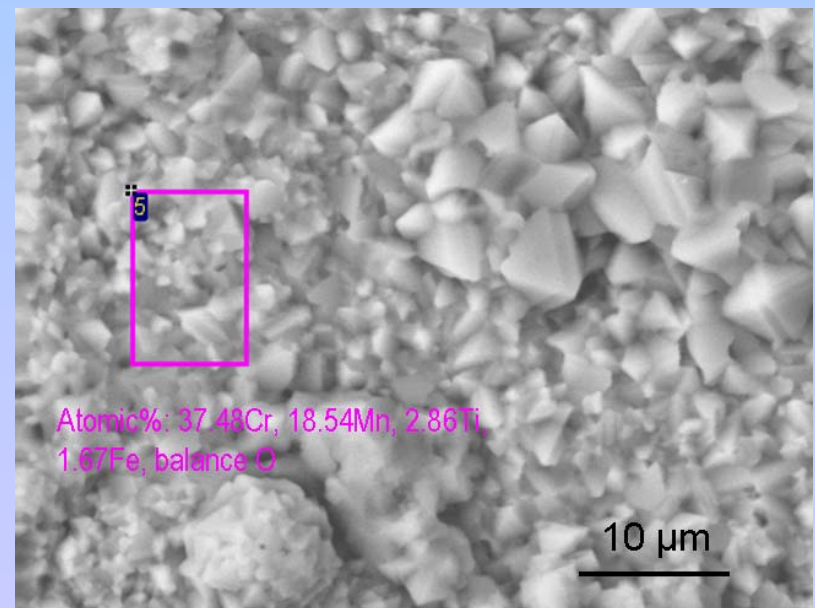


# Scale Structure and Compositions of 441

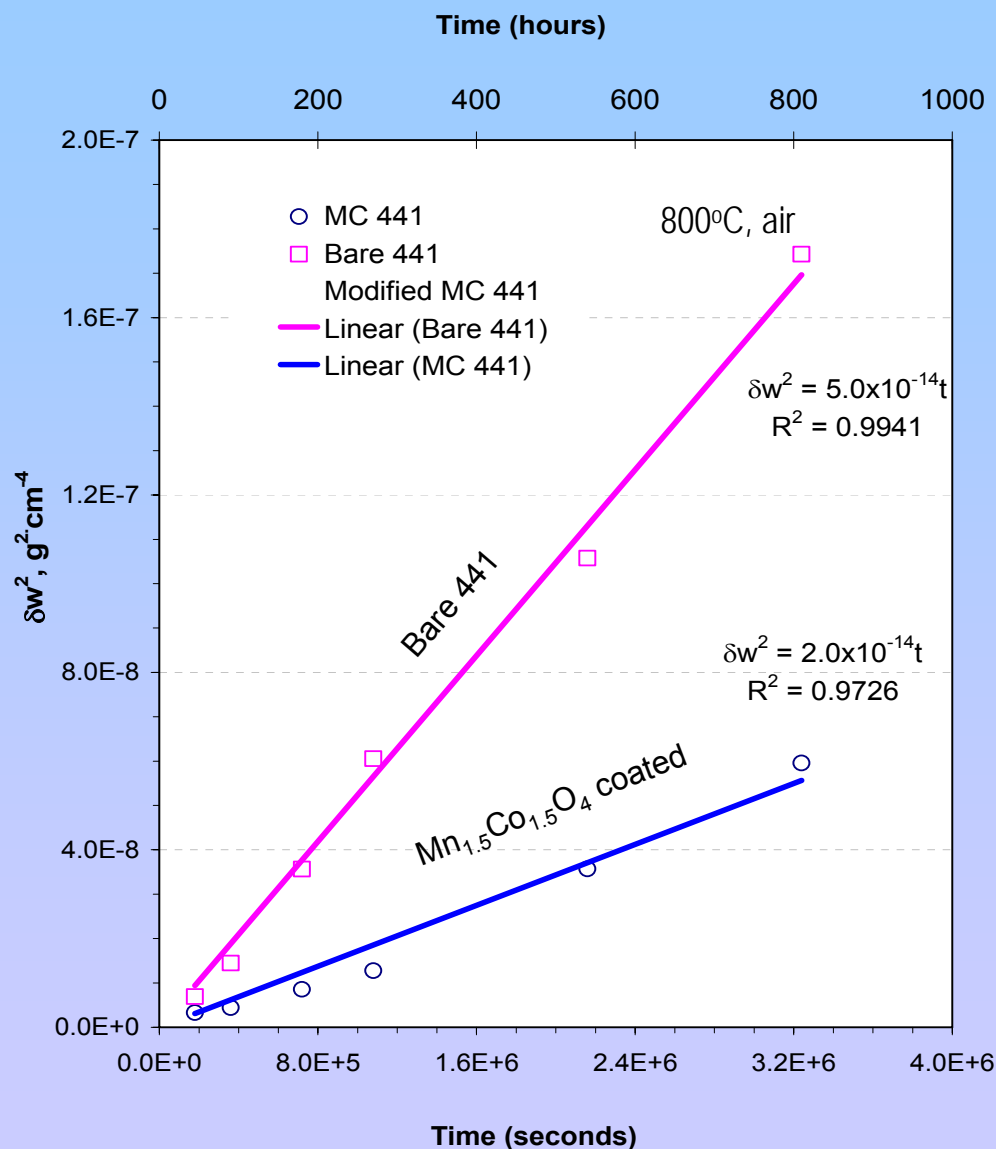
- Scale grown on 441 is mainly comprised of  $(\text{Mn,Cr})_3\text{O}_4$  and  $\text{Cr}_2\text{O}_3$ , similar to that of Crofer 22 APU
- Negligible Fe or iron oxides in the scale, different from that of 430



300 hours, 800°C, air



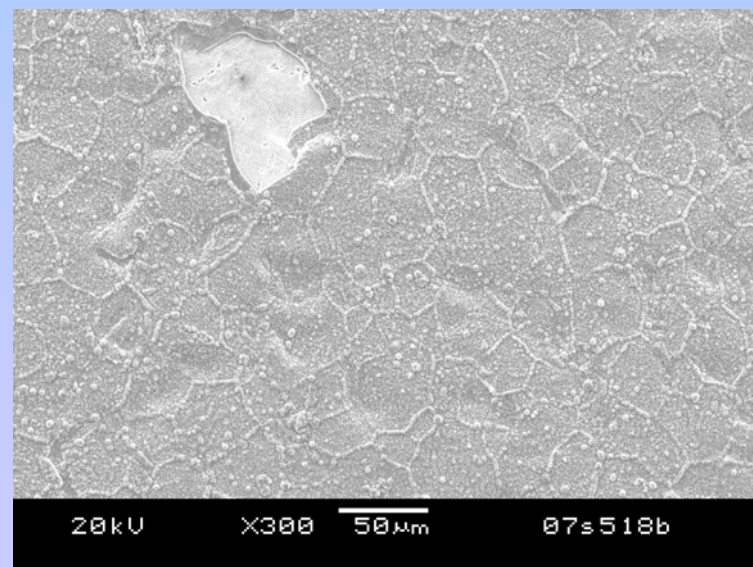
# Kinetics of Scale Growth on 441



○ Scale growth rate comparable to Crofer 22 APU, but with inferior scale adherence

(Local spallation found occasionally after extensive oxidation)

○ 2~3 times lower for MC coated specimens; no spallation

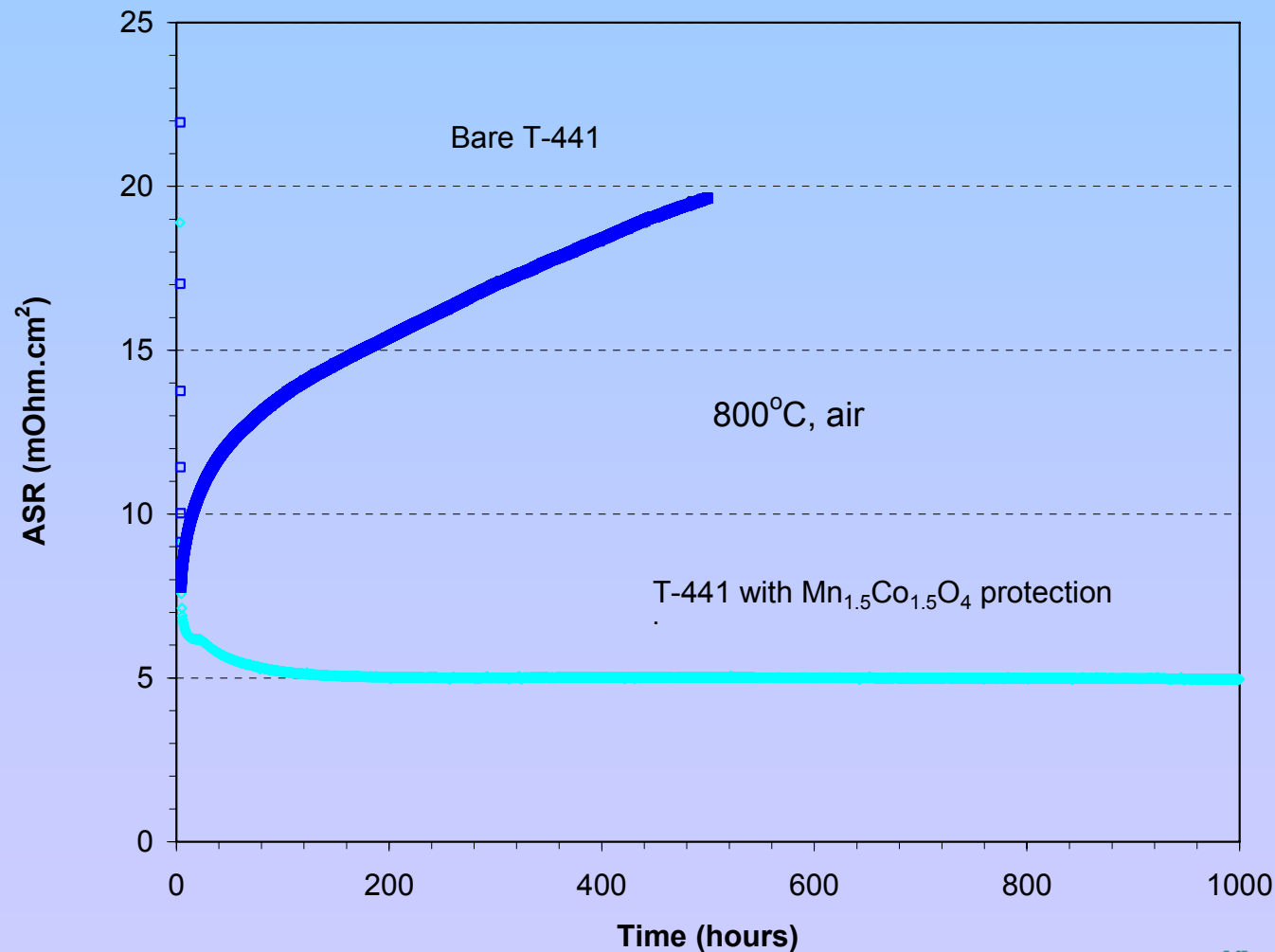


After 900 hours



# Electrical Performance of Surface-Modified 441

- $\text{Mn}_{1.5}\text{Co}_{1.5}\text{O}_4$  spinel protection layers minimized area specific electrical resistance (ASR)
- ASR of coated sample increased little, if any, over the course of the test



Cathode: LSM

Contact: LSM

IC: bare 441 or

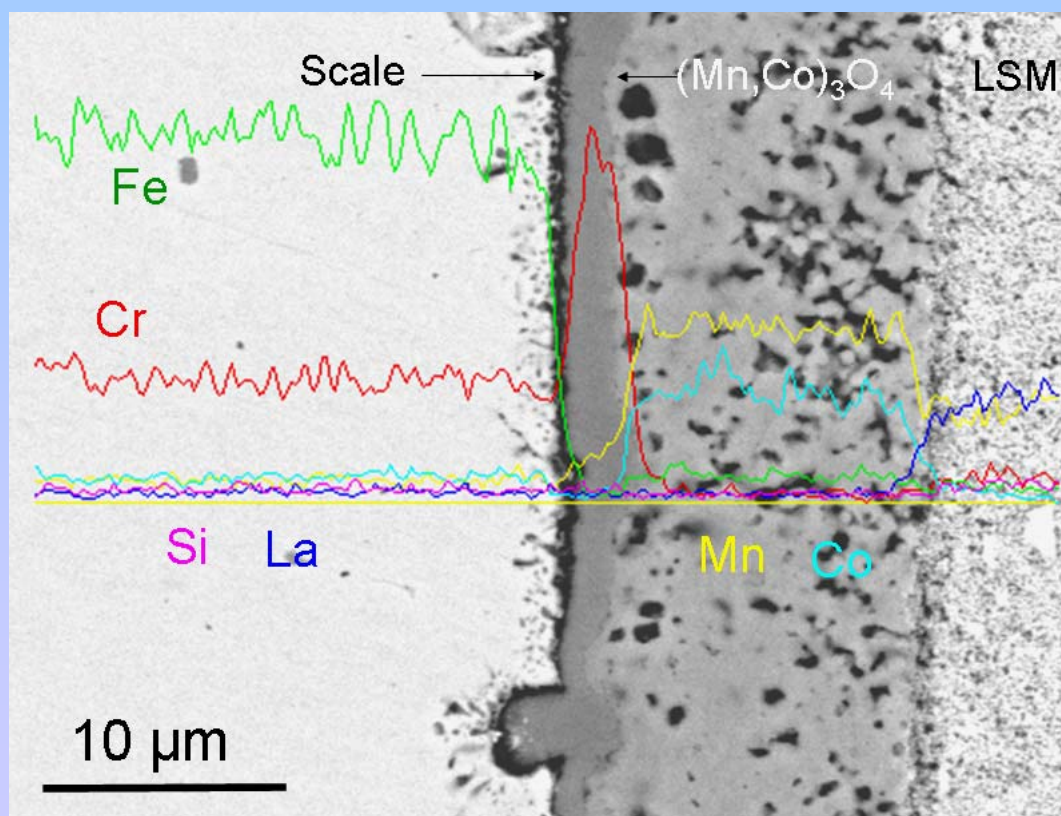
MC coated 441

Current:  $500 \text{ mA}\cdot\text{cm}^{-2}$

# SEM Cross-Sections of ASR Samples

- Improved surface stability: no spallation or detachment observed
- No penetration of Cr through the protection layer, though there appeared Fe migration into the coating (similar to 430).

MC coated 441



BS image

## Summary

- ❑ 441 exhibited promising alloy chemistry: addition of a small amount of Nb helps avoid formation of a continuous silica layer and promote desirable second phase precipitation, thus leading to a lower scale resistance and higher mechanical strength.
- ❑ The alloying approach eliminates the costly refining process that is currently employed for making Crofer 22 APU and other super-grade ferritic stainless steels for IC applications .
- ❑ Protection layers are required to further improve alloy surface stability and electrical performance, and seal off Cr.

## Future Work

- ❑ Evaluate long-term thermal stability and electrical performance of bare and surface modified 441
- ❑ Further understand the alloy chemistry via advanced diagnostic study
- ❑ Investigate and optimize bulk alloy chemistry and surface modification for satisfactory long-term stability and performance. (In collaboration with Allegheny Ludlum Corp.)



# Protection Layer Development and Investigation

- ◆ **Goal:** develop cost-effective, optimized protection layers that are effective barriers to both oxygen inward and chromium outward diffusion, while being stable over lifetime of SOFC operation.

## Previous work:

- Developed spinel protection layers with a nominal composition  $\text{Mn}_{1.5}\text{Co}_{1.5}\text{O}_4$
- Systematically studied  $(\text{Mn},\text{Co})_3\text{O}_4$  spinel materials
- Developed slurry-based approaches for fabrication of the spinel protection layers
- Evaluated kinetics of scale growth, stability under thermal cycling, electrical and electrochemical performance, chromia volatility, etc., of coated Crofer 22 APU
- Completed one year thermal stability evaluation of coated Crofer 22 APU

## Recent Accomplishments:

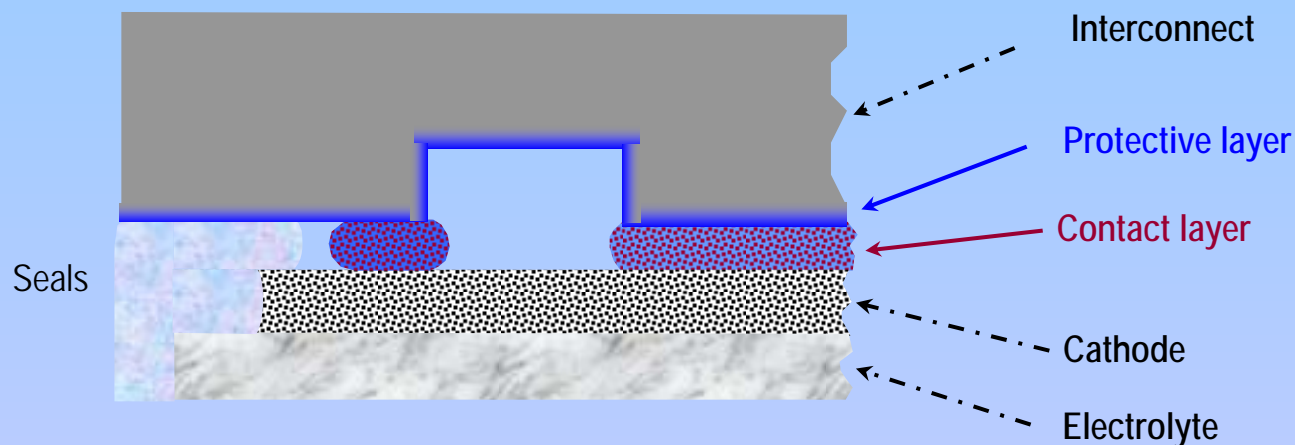
- Completed half year electrical evaluation of MC coated Crofer 22 APU and 430 (with LSM cathode & contact paste)
- Investigated suitability and performance of the spinel protection layers on 430 and 441 (see previous slides)
- Started developing alternative fabrication approaches, e.g. electrochemical deposition

# Summary and Future Work

- ❑ Spinel protection layers with a nominal composition  $\text{Mn}_{1.5}\text{Co}_{1.5}\text{O}_4$  and fabricated with slurry coating approaches are an effective oxygen inward and chromium outward diffusion barrier, mitigating scale growth and sealing off chromium
- ❑ Interconnect FSS, e.g. Crofer 22 APU, with the spinel protection layers demonstrated excellent long-term stability and electrical performance
- ❑ Developing cost-effective approaches compatible with mass production and practical shapes of interconnect
  - ❖ Electroplating, electrophoresis, etc., in addition to spray process.

# Contact Layer Investigation and Development

- ◆ **Goal:** develop cost-effective, optimized contact layers between metallic interconnects and electrodes.



## Functions

- Promote electrical contact
- Facilitate stack assembling
- Act as a potential buffer zone to prevent unwanted reactions and transport, such as Cr volatility

## Challenges

- A metallurgical bond can be built between a metallic interconnect and Ni-YSZ anode, providing a low resistance path for electrons.
- Oxide-metal interfaces are present between metallic interconnects and cathodes, increasing electrical resistance and thus causing power loss.

# Previous Work and Current Strategy

## Previous work and accomplishments:

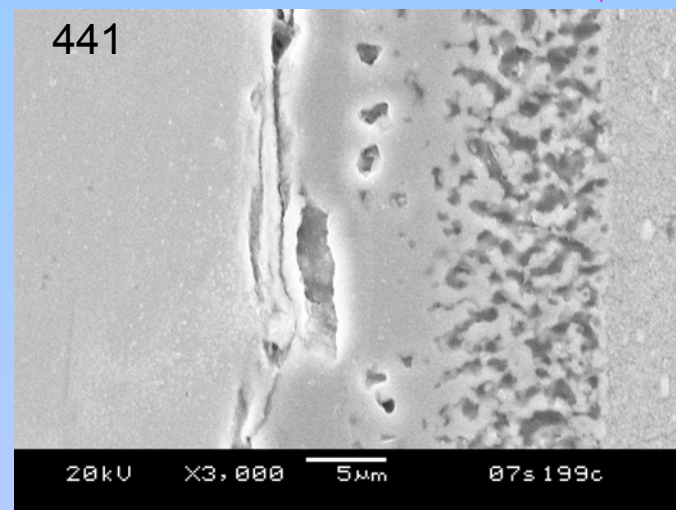
- Evaluated metals and varied conductive oxides, including LSM, LSCo, LSCM, MC, etc.
- Investigated interfacial interactions
- Initiated enhanced sintering approaches for LSM and MC

## Challenges of current materials

- ❑ Precious metals demonstrate suitable properties, but too expensive (Ag, a possible exception).
- ❑ Conductive oxides of high sintering activity, e.g. superconductors, usually too reactive, negatively affecting the stack and interface stability
- ❑ Conductive oxides, e.g. LSM, that are typically used as cathode compositions demonstrated good compatibility, but need improvement in sintering activity at 800-900°C and thus better electrical contact

**Approach:** improve sintering activity via reaction sintering, addition of sintering agents or chemical modification

Spinel protection layer  
↓ LSM contact



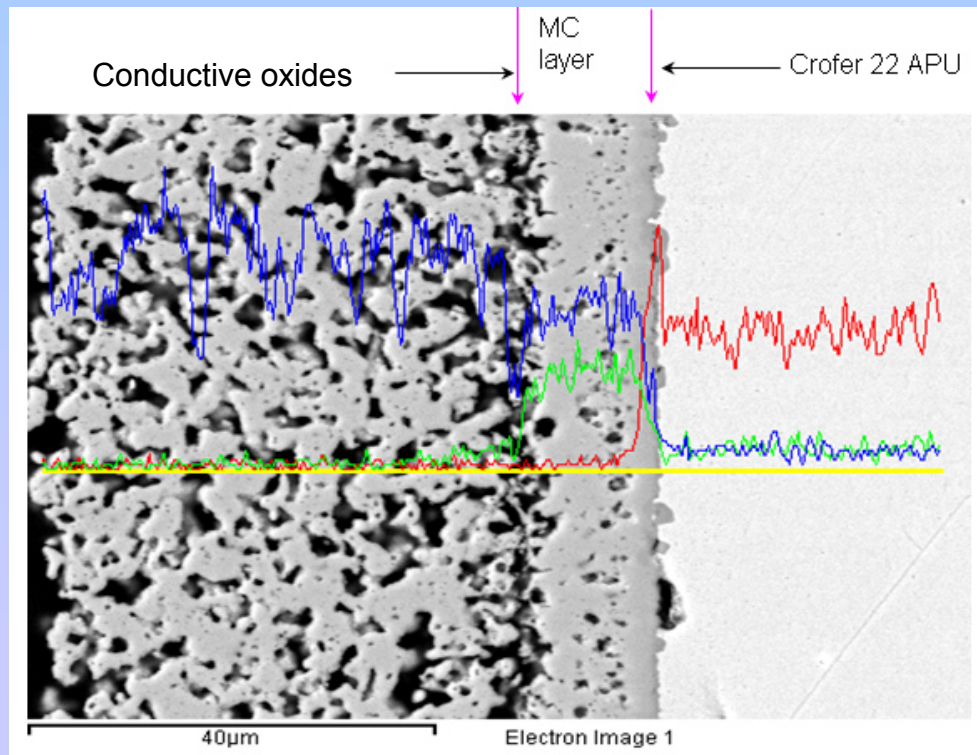
# Fabrication of Contact Layers via Reaction Sintering

Paste of metals and/or oxides mixture

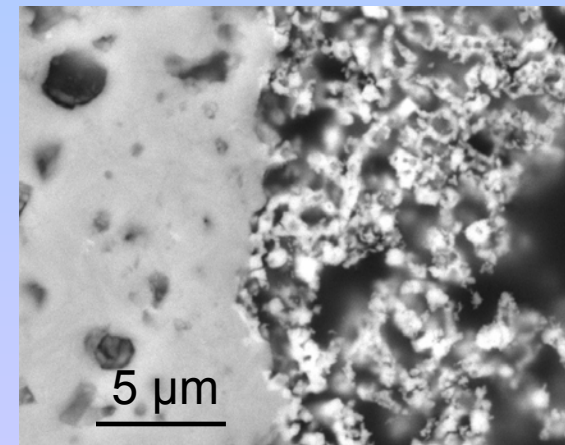
During first stack heating or sealing

Conductive oxide contact layer

Reactions assisted sintering



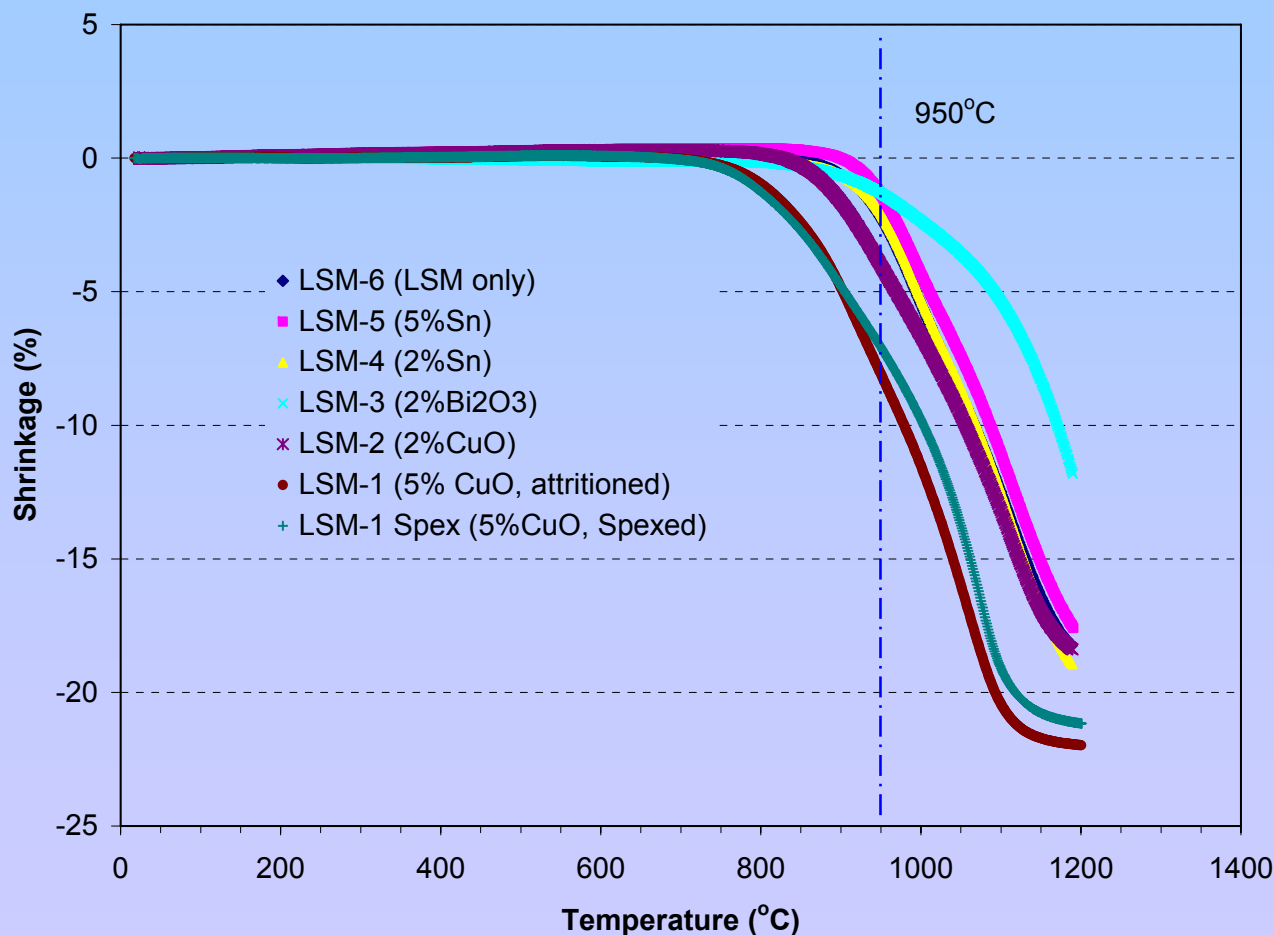
After reaction sintering



Without sintering

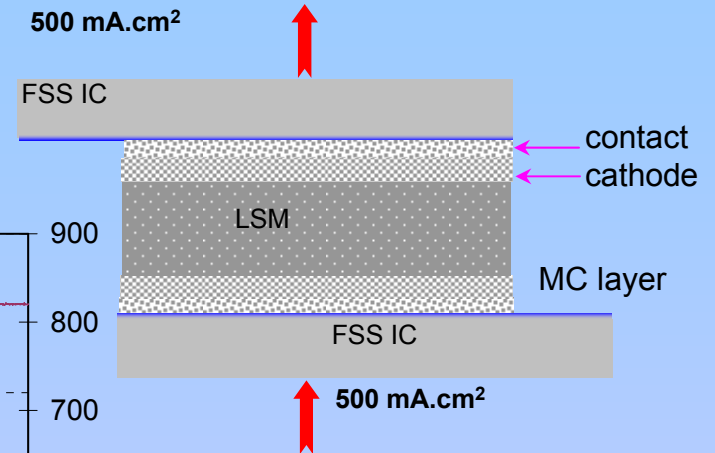
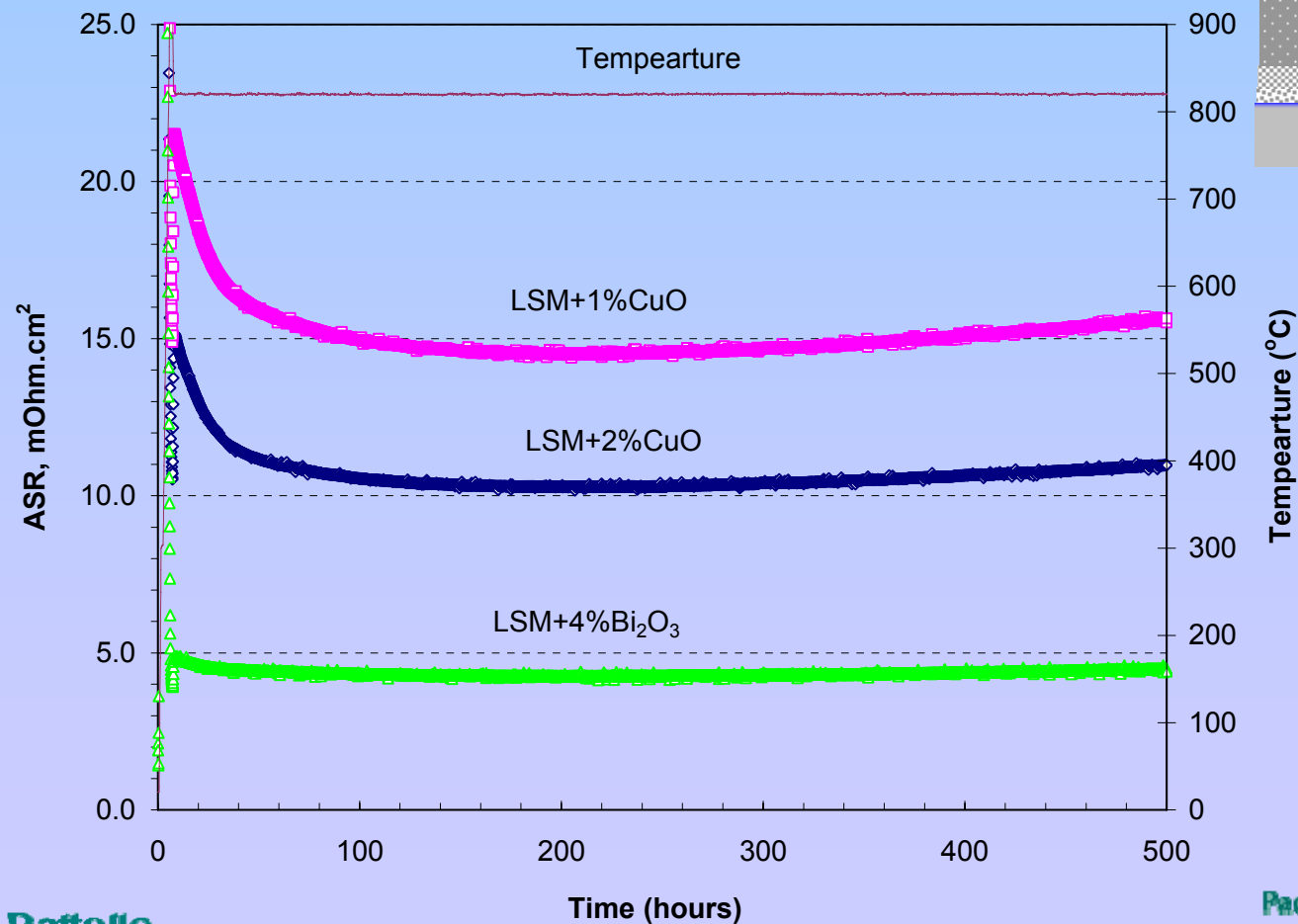
# Contac Layers via Adding Sintering Agents

- Among studied, CuO and  $\text{Bi}_2\text{O}_3$  more effective for LSM
- To be effective needs 4~5%

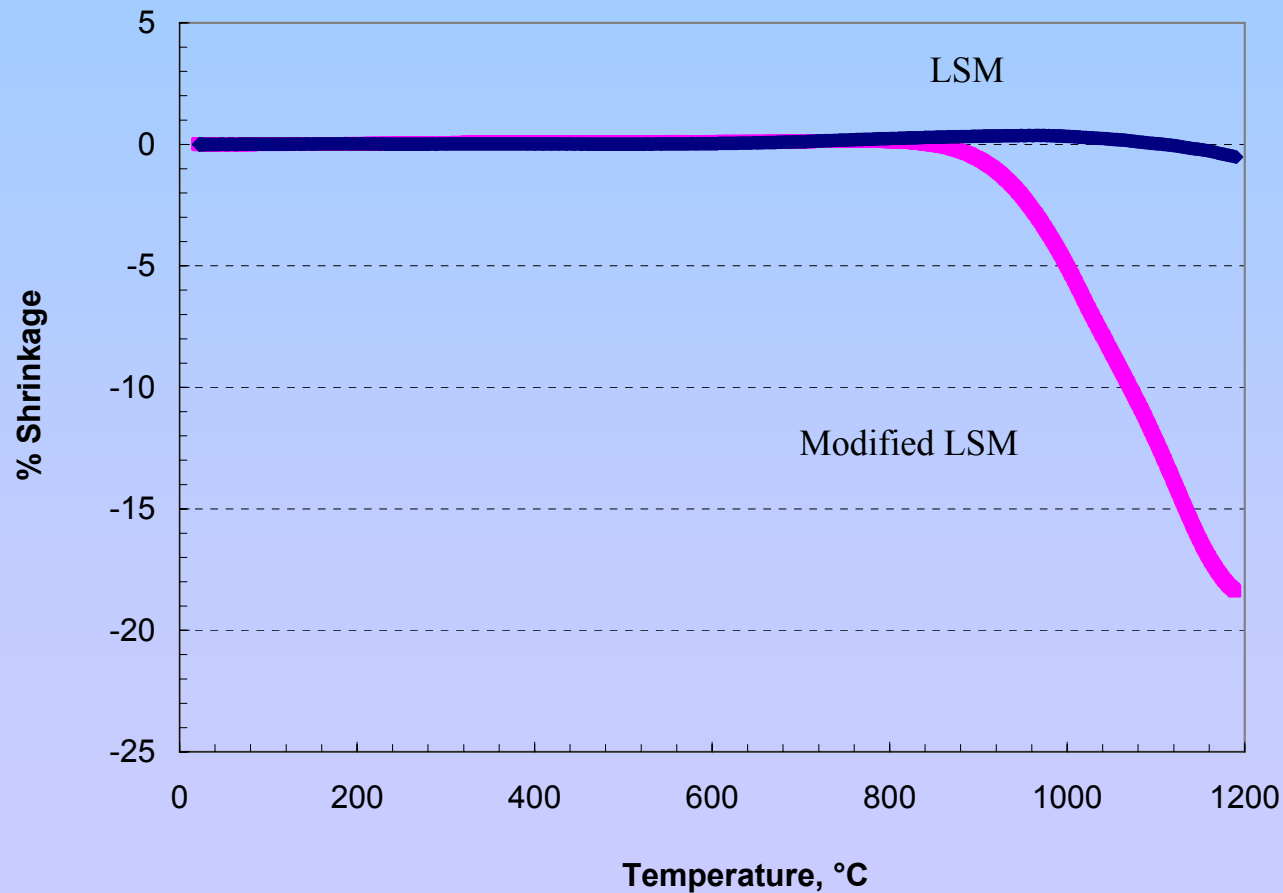


# Electrical Performance and Stability Evaluation

Interfacial resistance evaluation unit (IRU)



# Enhanced Sintering via Chemical Modifications





## Summary

- ✚ Reaction sintering appears to be a promising approach to fabricate contact layers between perovskite cathodes and metallic interconnects.
- ✚ Addition of sintering aids and chemistry modifications also help improve sintering activity of conductive oxides.

## Future work

- Continue to search and optimize contact materials and processing approaches
- Systematically evaluate candidate systems: dilatometry, IRU (ASR), SEM, XRD.
- Evaluate long term electrical performance and interface stability under isothermal and thermal cycling

## Acknowledgements

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